

# SLI12N65SV / SLB12N65SV

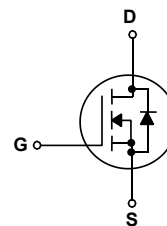
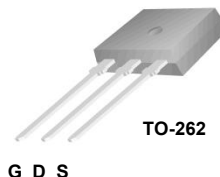
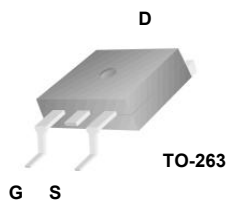
## 650V N-Channel MOSFET

### General Description

This Power MOSFET is produced using Msemitek's advanced planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction based on half bridge topology.

### Features

- 12A, 650V,  $R_{DS(on)Type} = 0.64\Omega @ V_{GS} = 10V$
- Low gate charge ( typical 45nC)
- High ruggedness
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	SLI12N65SV	SLB12N65SV	Units
$V_{DSS}$	Drain-Source Voltage	650		V
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ ) - Continuous ( $T_C = 100^\circ\text{C}$ )	12		A
		6		A
$I_{DM}$	Drain Current - Pulsed (Note 1)	40		A
$V_{GSS}$	Gate-Source Voltage	$\pm 30$		V
EAS	Single Pulsed Avalanche Energy (Note 2)	550		mJ
$I_{AR}$	Avalanche Current (Note 1)	12		A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	36		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	2.1		V/ns
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ ) - Derate above $25^\circ\text{C}$	-	41.7	W
		-	0.33	W/ $^\circ\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150		$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300		$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Max		Units
		SLI12N65SV	SLB12N65SV	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	-	3.0	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	$^\circ\text{C}/\text{W}$

## Package Marking

Part Number	Top Marking	Package	Packing Method	MOQ	QTY
SLI12N65SV	SLI12N65SV	TO-262	Tube	1000	5000
SLB12N65SV	SLB12N65SV	TO-263	Tape	800	4000

## Electrical Characteristics

 $T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### Off Characteristics

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	650	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	-	--	$V/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}$	--	--	10	$\mu\text{A}$
		$V_{DS} = 520\text{ V}, T_C = 125^\circ\text{C}$	--	--	100	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2.0	--	4.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 6\text{ A}$	--	0.64	0.8	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 40\text{ V}, I_D = 6\text{ A}$ (Note 4)	--	11	--	S

### Dynamic Characteristics

$C_{ISS}$	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	--	2230	--	pF
$C_{OSS}$	Output Capacitance		--	370	--	pF
$C_{RSS}$	Reverse Transfer Capacitance		--	130	--	pF

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 320\text{ V}, V_{GS} = 10\text{ V}, I_D = 12\text{ A}, R_G = 25\text{ }\Omega$ (Note 4, 5)	--	25	--	ns
$t_r$	Turn-On Rise Time		--	50	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	45	--	ns
$t_f$	Turn-Off Fall Time		--	30	--	ns
$Q_g$	Total Gate Charge	$V_{DS} = 520\text{ V}, I_D = 12\text{ A}, V_{GS} = 10\text{ V}$ (Note 4, 5)	--	45	--	nC
$Q_{GS}$	Gate-Source Charge		--	8.4	--	nC
$Q_{GD}$	Gate-Drain Charge		--	10	--	nC

### Drain-Source Diode Characteristics and Maximum Ratings

$I_S$	Maximum Continuous Drain-Source Diode Forward Current	--	--	12	A	
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	40	A	
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 12\text{ A}$	--	--	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = 12\text{ A},$	--	300	--	ns
$Q_{rr}$	Reverse Recovery Charge	$di_F / dt = 100\text{ A}/\mu\text{s}$ (Note 4)	--	2.0	--	$\mu\text{C}$

#### Notes:

- Repetitive Rating : Pulse width limited by maximum junction temperature
- $L = 11\text{ mH}, I_{AS} = 10\text{ A}, V_{DD} = 50\text{ V}, R_G = 25\text{ }\Omega$ , Starting  $T_J = 25^\circ\text{C}$
- $I_{SD} \leq I_D, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ\text{C}$
- Pulse Test : Pulse width  $\leq 300\text{ }\mu\text{s}$ , Duty cycle  $\leq 2\%$
- Essentially independent of operating temperature

### N- Channel Typical Characteristics

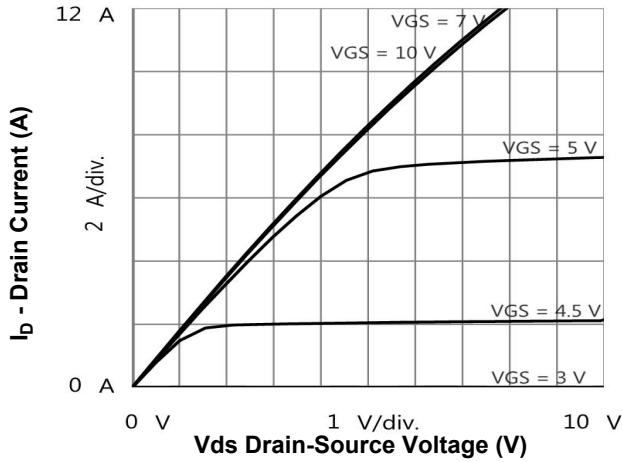


Figure 1. On-Region Characteristics

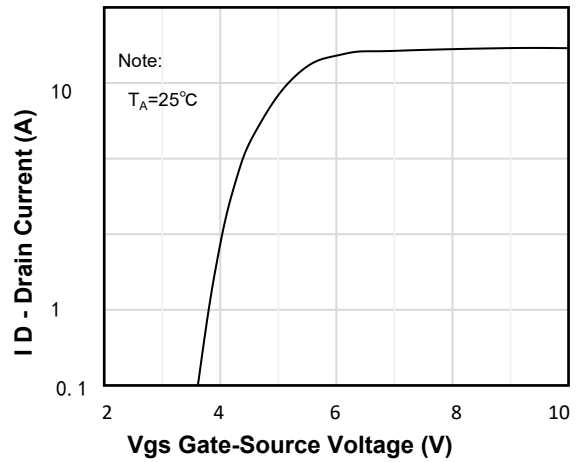


Figure 2. Transfer Characteristics

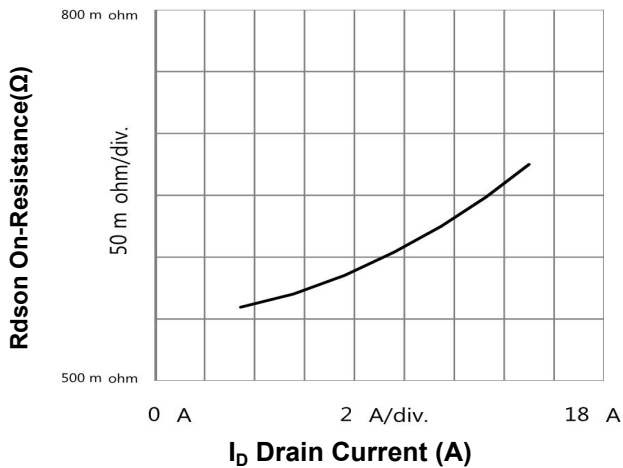


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

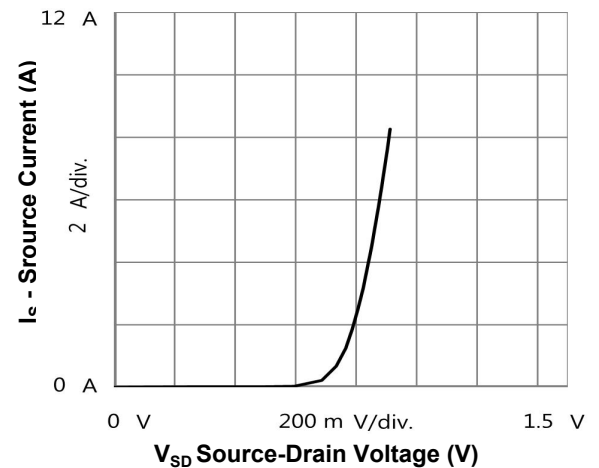


Figure 4. Source Current vs Source-Drain Voltage

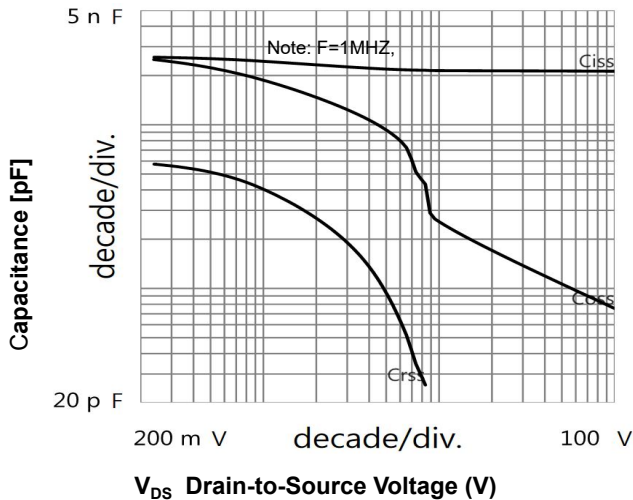


Figure 5.1 Capacitance Characteristics

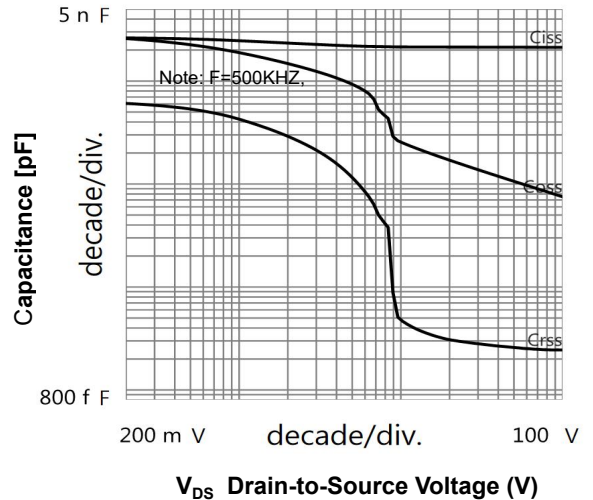
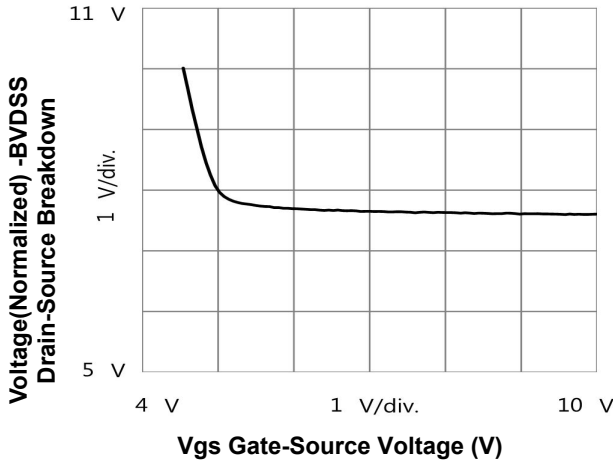
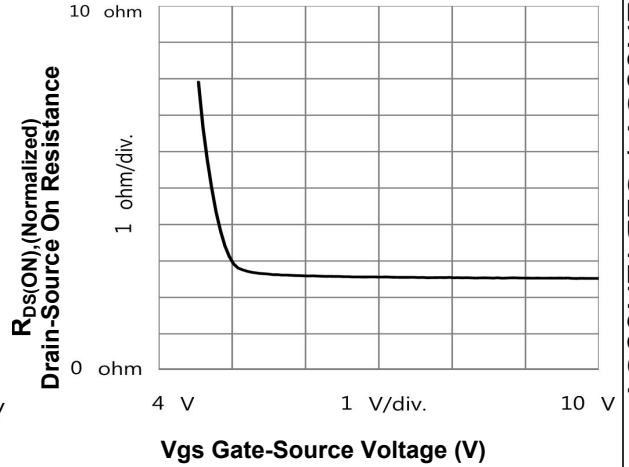


Figure 5.2 Capacitance Characteristics

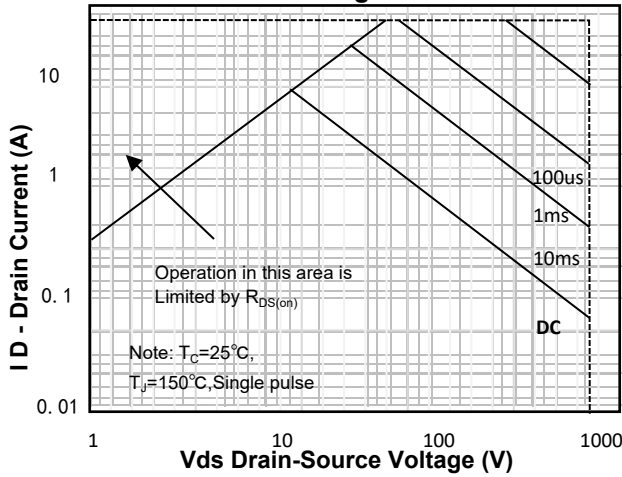
**N- Channel Typical Characteristics** (Continued)



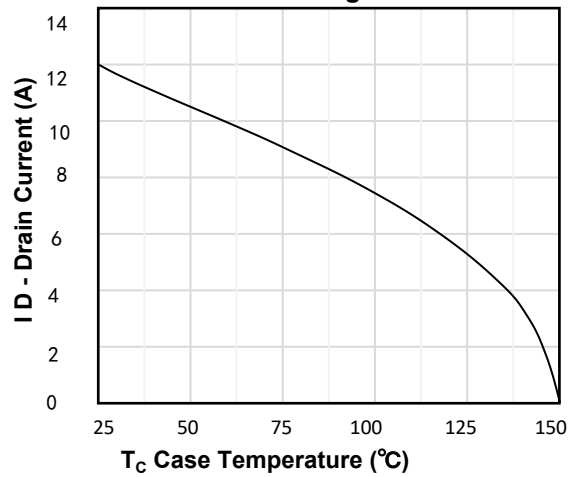
**Figure 7. Breakdown Voltage Variation vs Gate-Source Voltage**



**Figure 8. On-Resistance Variation vs Gate-Source Voltage**

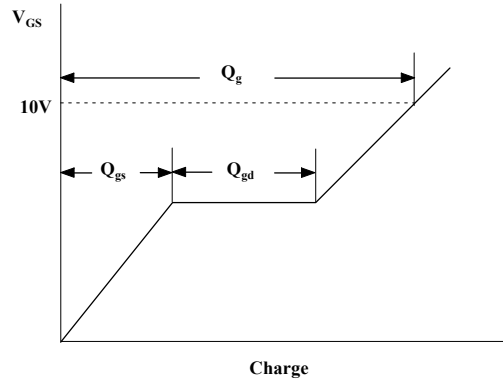
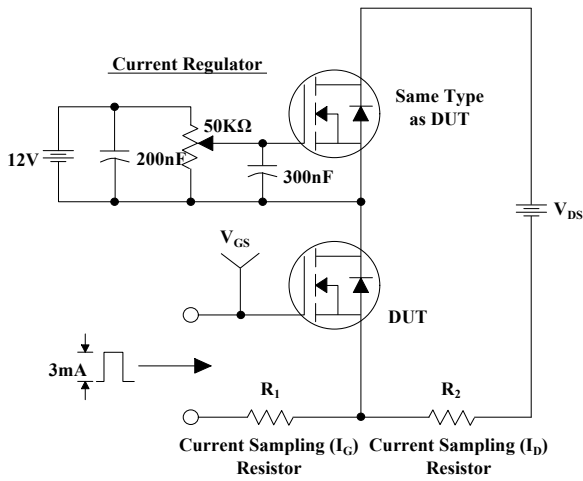


**Figure 9. Maximum Safe Operating Area**

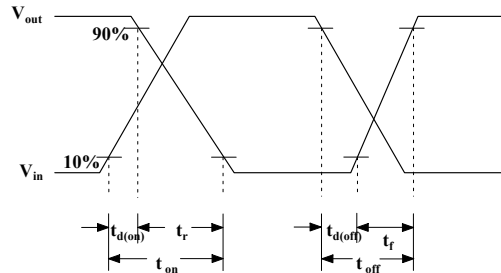
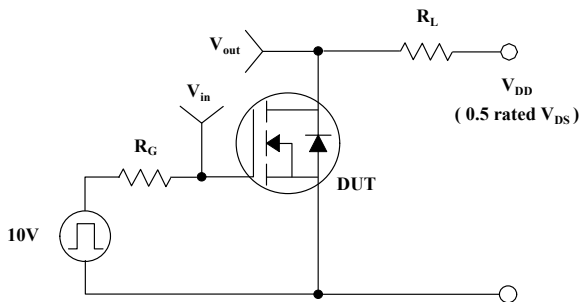


**Figure 10. Maximum Drain Current vs Case Temperature**

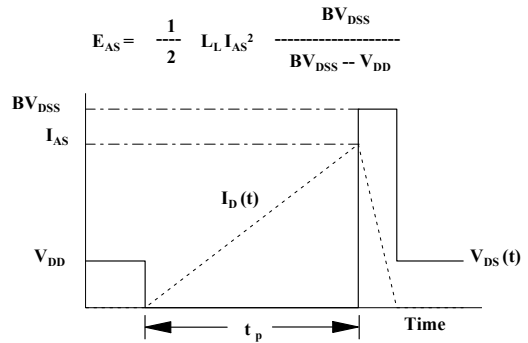
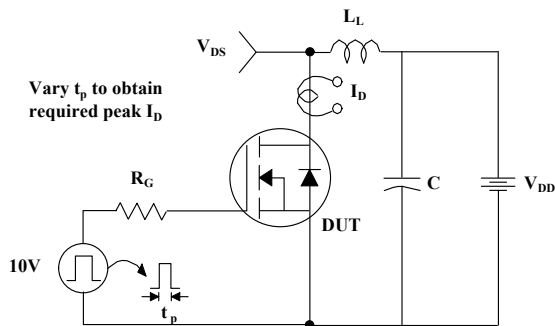
### Gate Charge Test Circuit & Waveform



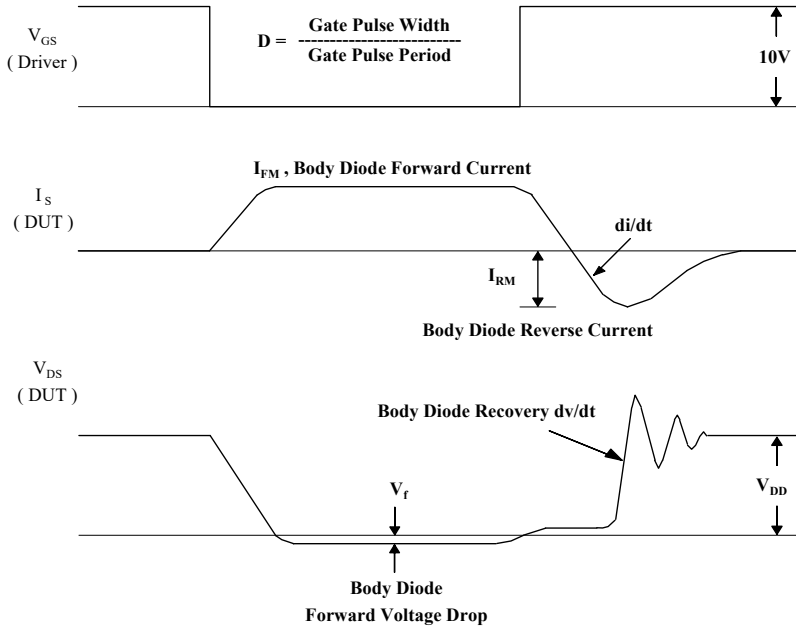
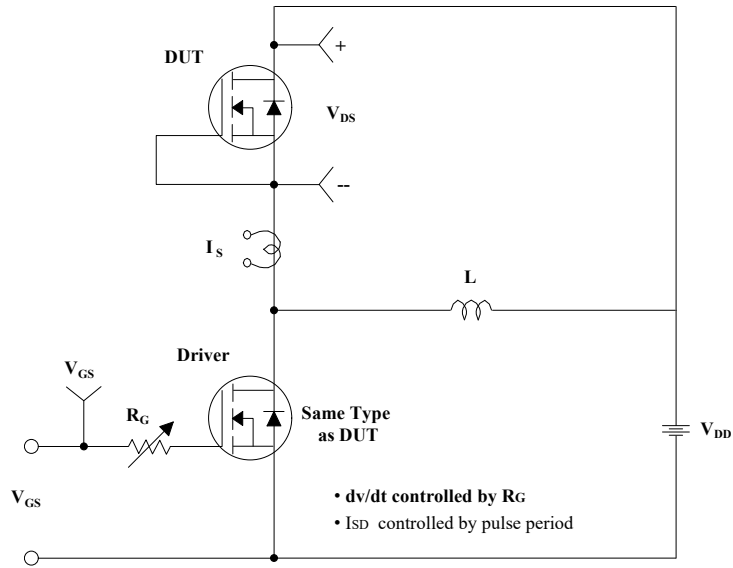
### Resistive Switching Test Circuit & Waveforms



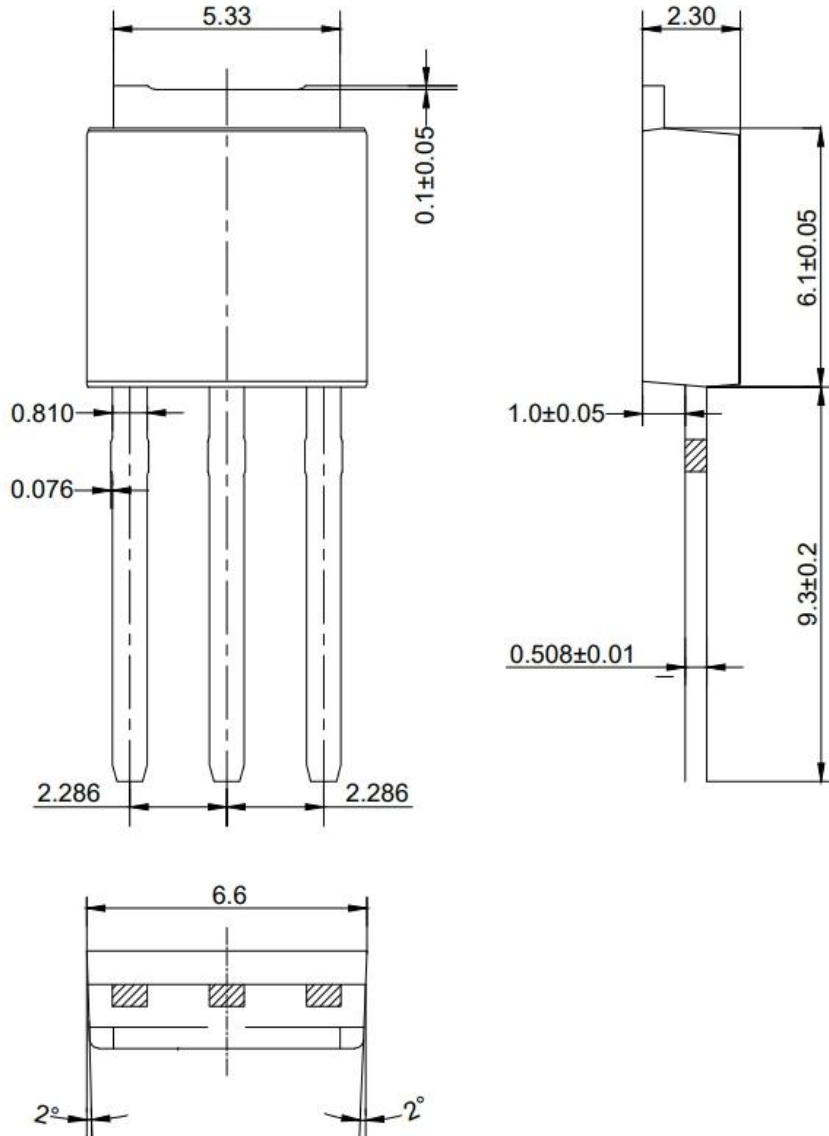
### Unclamped Inductive Switching Test Circuit & Waveforms



## Peak Diode Recovery dv/dt Test Circuit & Waveforms



## TO-251 OUTLINE

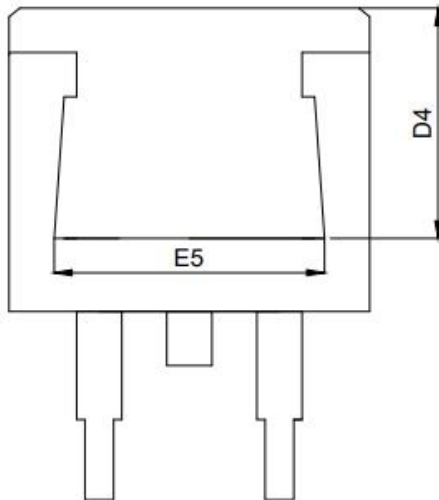
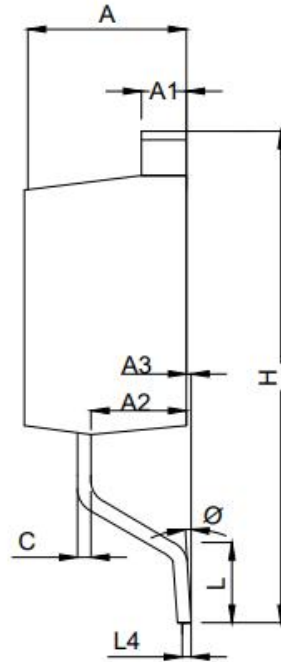
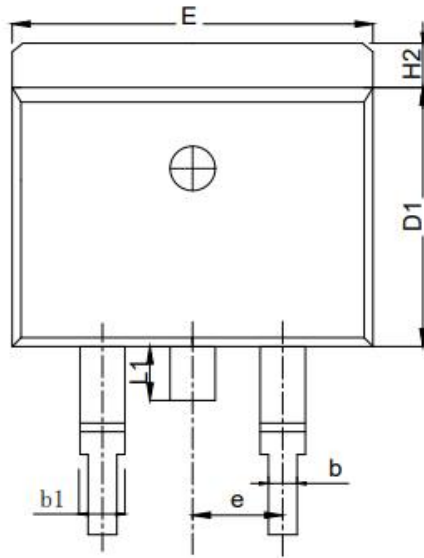


## Note:

1,Unit: millimeters

2,The tolerance not noted is  $\pm 0.15$ , and the unmarked fillet  $R_{max} = 0.25$

# TO-263 OUTLINE



Symbol	DIMENSIONS (unit:mm)		
	Min	Typ	Max
A	4.37	4.57	4.77
A1	1.22	1.27	1.42
A2	2.49	2.69	2.89
A3	0	0.13	0.25
b	0.7	0.81	0.96
b1	1.17	1.27	1.47
c	0.3	0.38	0.53
D1	8.5	8.7	8.9
D4	6.6	-	-
E	9.86	10.16	10.36
E5	7.06	-	-
e	2.54 BSC		
H	14.7	15.1	15.5
H2	1.07	1.27	1.47
L	2	2.3	2.6
L1	1.4	1.55	1.7
L4	0.25 BSC		
?	0°	5°	9°

**NOTE:**

- 1The plastic package is not marked as smooth surfaceRa=0.1;Subglossy surfaceRa=0.8
- 2.Undeclared tolerance  $\pm 0.25$ ,Unmarked filletRmax=0.25



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